

Number	Hits	Search Text	DB	Time stamp
1	0	cho-jin-wick.in.	USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM_TDB	2013/07/17 11:31
2	0	xue hongxi.in.	USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM_TDB	2013/07/17 11:33
3	0	substrate and heat adj sink element plate plus spread04 with bump with emitters and metallizat04	USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM_TDB	2013/07/17 11:35
4	119	substrate and heat adj sink element plate plus spread04 and emitters and metallizat04	USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM_TDB	2013/07/17 13:40
5	0	"8848138" .IN.	USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM_TDB	2013/07/17 15:16
6	0	"8848466" .IN.	USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM_TDB	2013/07/17 17:47
7	4	"8848138" ; "8848466" .IN.	USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM_TDB	2013/07/17 17:49
8	0	"8848138"	USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM_TDB	2013/07/17 18:04
9	0	"8848138"	USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM_TDB	2013/07/17 18:09
10	211	substrate and heat adj sink element plate plus spread04 and bump and transist01	USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM_TDB	2013/07/17 18:19
11	0	substrate and heat adj sink element plate plus spread04 with bump with emitter	USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM_TDB	2013/07/17 18:24
12	0	heat adj sink element plate plus spread04 with bump with emitter	USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM_TDB	2013/07/17 18:25
13	0	heat adj sink element plate plus spread04 with emitter	USPAT; US-PGPUB; EPC; JPC; DERWENT; IBM_TDB	2013/07/17 18:25

1	257/678,734,735-737.coils. and heat adj	USPAT:	2000/07/16
	sink element plate plug spread04 with	US-PGPUB:	19:04
	emitter and bump ball	EPIC / CPC;	
		DEPWENT;	
		IRM TDR	
4	"4994932" or "5478240" .RM.	USPAT:	2000/07/16
		US-PGPUB:	19:04
		EPIC / CPC;	
		DEPWENT;	
		IRM TDR	
15	chip die IC with emitter and bump	USPAT:	2000/07/16
	ball and heat adj; sink element plate	US-PGPUB:	19:04
	plug spread04	EPIC / CPC;	
		DEPWENT;	
		IRM TDR	
55	257/710,737-738 chip die IC with emitter	USPAT:	2000/07/16
	and bump ball and heat adj; sink	US-PGPUB:	19:04
	element plate plug spread04	EPIC / CPC;	
		DEPWENT;	
		IRM TDR	
4	257/718,737-738.coils. and chip die IC	USPAT:	2000/07/16
	with emitter and bump ball and heat	US-PGPUB:	19:04
	adj; sink element plate plug spread04	EPIC / CPC;	
		DEPWENT;	
		IRM TDR	
3	257/710,737-738.coils. and flip adj; chip	USPAT:	2000/07/16
	with emitter and heat adj; sink element	US-PGPUB:	19:04
	plate plug spread04	EPIC / CPC;	
		DEPWENT;	
		IRM TDR	
3	257/678,734,735-737.coils. and flip adj;	USPAT:	2000/07/16
	chip with emitter and heat adj; sink	US-PGPUB:	19:04
	element plate plug spread04	EPIC / CPC;	
		DEPWENT;	
		IRM TDR	
14	flip adj; chip with emitter and heat	USPAT:	2000/07/16
	adj; sink element plate plug spread04	US-PGPUB:	19:04
		EPIC / CPC;	
		DEPWENT;	
		IRM TDR	